“Hot” for Warm Water Cooling

FEDERAL PARTNERSHIP
for
GREEN DATA CENTERS
January 25, 2012

BERKELEY LAB

Bill Tschudi
wftschudi@lbl.gov
Lawrence Berkeley National Laboratory

Energy Efficient
High Performance Computing Working Group
(EE HPC WG)

- Initially formed by FEMP to drive energy efficient design and operation of HPC facilities and influence efficiency of High Performance Computers
- Demonstrate leadership in energy efficiency as well as computing performance
- Forum for sharing of information (peer-to-peer exchange) and collective action
- Collaboration with industry groups and HPC manufacturers

http://eehpcwg.lbl.gov

BERKELEY LAB
Lawrence Berkeley National Laboratory

EE HPC WG

- Participants from DOE National Laboratories, Academia, various Federal Agencies, and International stakeholders
- HPC vendor participation
- Working Group selects energy related topics to develop
- Organized and led by Lawrence Berkeley National Laboratory supported by the DOE Sustainability Performance Office

Liquid Cooling Thermal Guidelines

Goal: Encourage highly efficient liquid cooling through use of high temperature fluids delivered to cool IT equipment

- Eliminate or dramatically reduce use of compressor cooling (chillers); secondarily – reduce water use
- Standardize temperature requirements – Common understanding between IT mfgs and sites
- Ensure practicality of recommendations - Collaboration with IT manufacturers to develop attainable recommended limits
- Industry endorsement of recommended limits - Collaboration with ASHRAE to adopt recommendations in new thermal guidelines

“Hot” for Warm Water Cooling

paper presented at SC-11

PRIMARY AUTHORS:

Henry Coles
Lawrence Berkeley National Laboratory
hccoles@lbl.gov

Michael Ellsworth
IBM Corporation
mje@us.ibm.com

David J. Martinez
Sandia National Laboratory
davmart@sandia.gov

ADDITIONAL AUTHORS

Anna-Maria Bailey, LLNL
Farhad Banisadr, LANL
Natalie Bates, EE HPC WG
Susan Coghlan, Argonne
David Cowley, PNNL
Nicolas Dube, HP
Parks Fields, LANL
Steve Greenberg, LBNL
Madhusudan Iyengar, IBM
Peter Kulesza, ORNL
Josip Loncaric, LANL
Tim McCann, SGI
Greg Pautsch, Cray
Michael K. Patterson, Intel
Richard G. Rivera, LANL
Greg K. Rottman, US Army
Dale Sartor, LBNL
William Tschudi, LBNL
Wade Vinson, HP
Ralph Wescott, PNNL

What is driving liquid cooling?

- Total power and power density increasing
- PUE's are improving but high end is reaching limit of air cooling
- Liquid is a more efficient cooling medium
- Many flavors of liquid cooling –
  - Liquid at facility level (chilled water)
  - Modular in-row, rack, and rear door cooling solutions becoming popular
  - Liquid inside high density IT equipment to the server or to the processor
- The closer the liquid to the heat source, the more efficient the cooling
- Higher temperature liquid leaving IT equipment can facilitate heat re-use

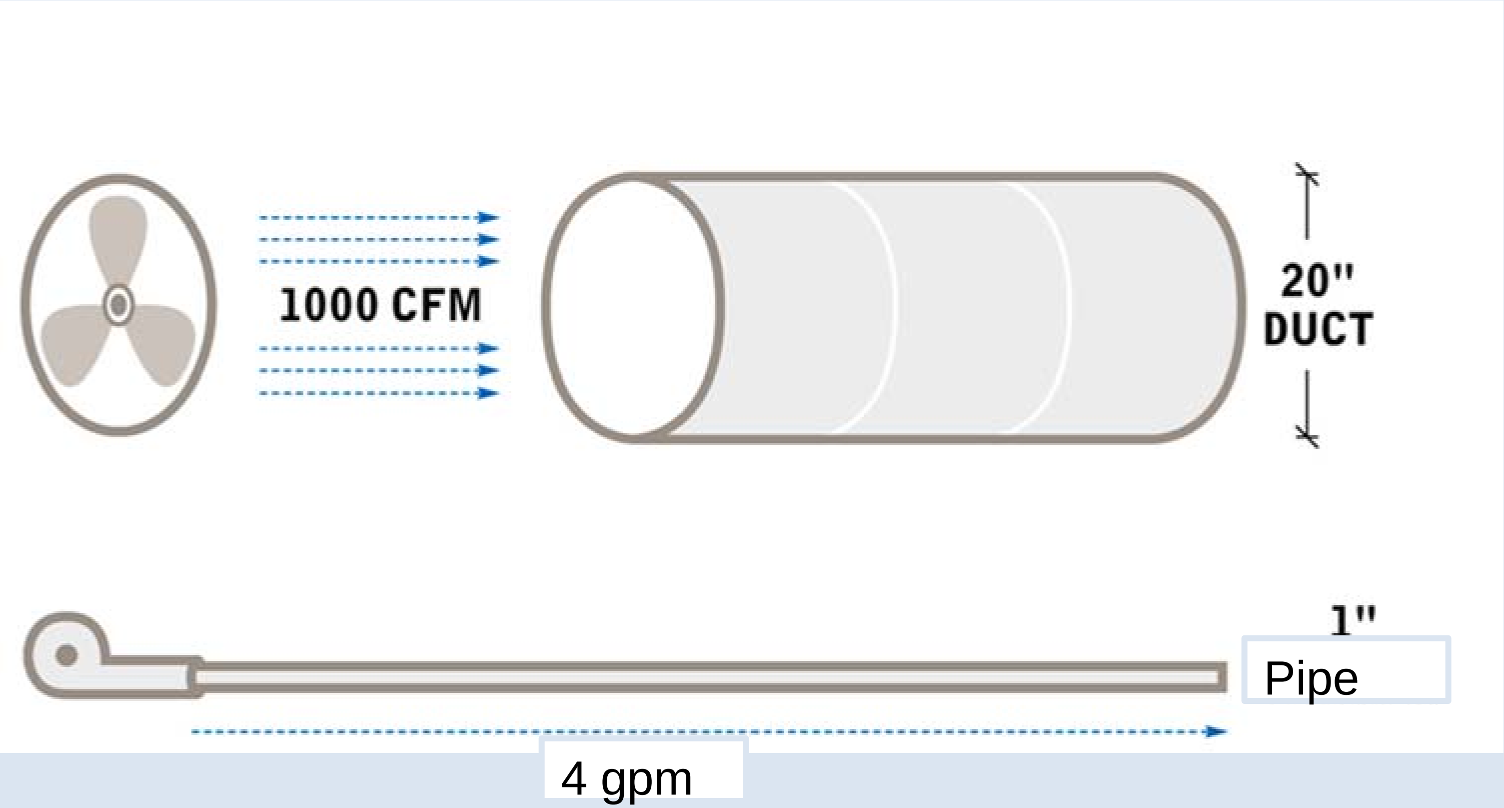
Liquid cooled IT equipment

- Many configurations use liquid to cool air-cooled IT equipment
  - Rack level cooling
  - Overhead cooling
  - Through row cooling
  - Rear door heat exchangers
- Cooling effectiveness is better closer to the heat source
  - More heat is captured - less air mixing, conduction, etc.
  - Closer to the heat source, higher temperatures can be used
  - Liquid cooling can eliminate the need for fans
- Different liquid solutions can utilize different temperature liquids

Liquids Move Energy More Efficiently

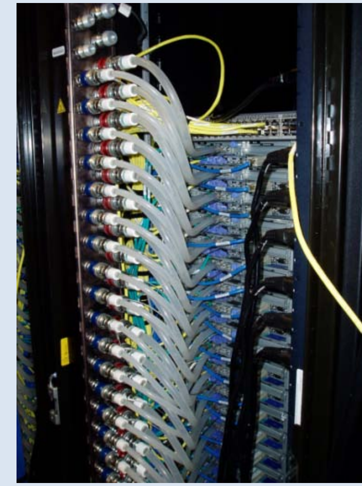
0.58 bhp
Fan

0.05 bhp
Pump



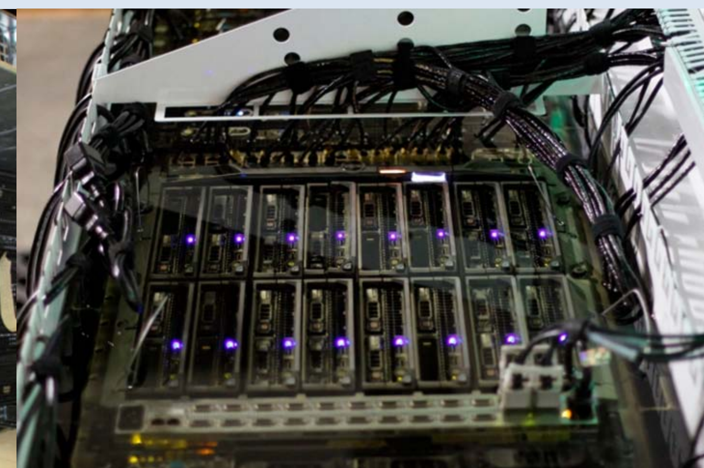
Flow		Formula	DT		BTUH	Eff	DP		Formula	BHP
1,000	cfm	BTUH=1.1*cfm*DT	21.8	°F	24,000	54%	2	in w.c.	bhp=cfm*DP/(6350*eff)	0.58
4	gpm	BTUH=500*gpm*DT	12.0	°F	24,000	80%	40	ft w.c.	bhp=gpm*DP/(3960*eff)	0.05

Types of liquid Solutions within IT equipment:



- Submersion in di-electric fluid (early Cray)
- Submersion in Oil (Green Revolution Cooling)
- Fluid to the server
- Fluid all the way to the CPU case (IBM)
- Di-electric fluid sprayed on CPU (Spraycool)
- Combination conduction and liquid cooled (Clustered Systems)
- Submersion in di-electric fluid (new 3M product)





General Approach to Develop Guidelines

Goal: Develop guidelines for liquid cooling temperatures at the inlet to IT equipment

- Determine climate conditions where National Laboratories are located
- Analyze systems that use evaporation (cooling towers) or dry coolers for ultimate heat rejection to atmosphere
- Model heat transfer from the processor to atmosphere
- Determine consensus of thermal margin to critical processor temperatures
- Obtain industry buy in for recommended temperatures

Methods

Determine National Laboratory locations and obtain ASHRAE Dry Bulb and Wet Bulb ASHRAE Design Data for 99.6% of conditions (all but a few hours per year)

Develop Cooling Architectures without compressors

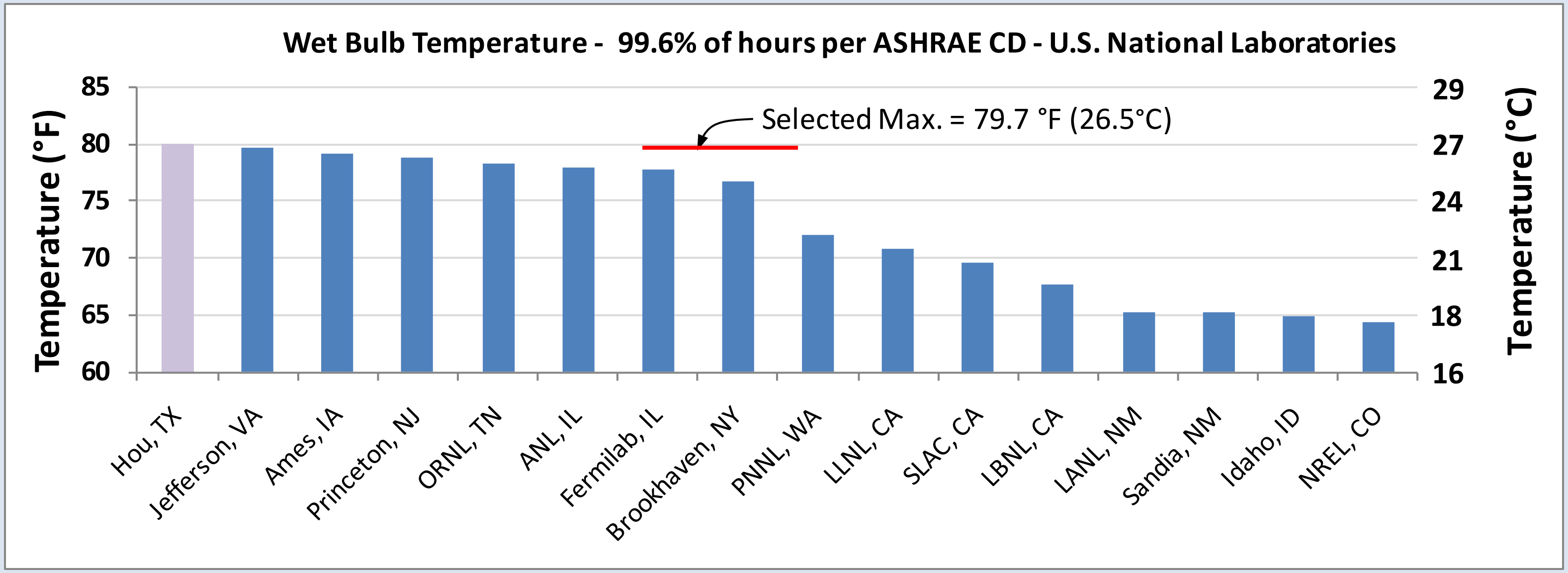
- Cooling towers – evaporative cooling limited by wet bulb temperature
- Dry coolers – air to air heat exchange limited by dry bulb temperature

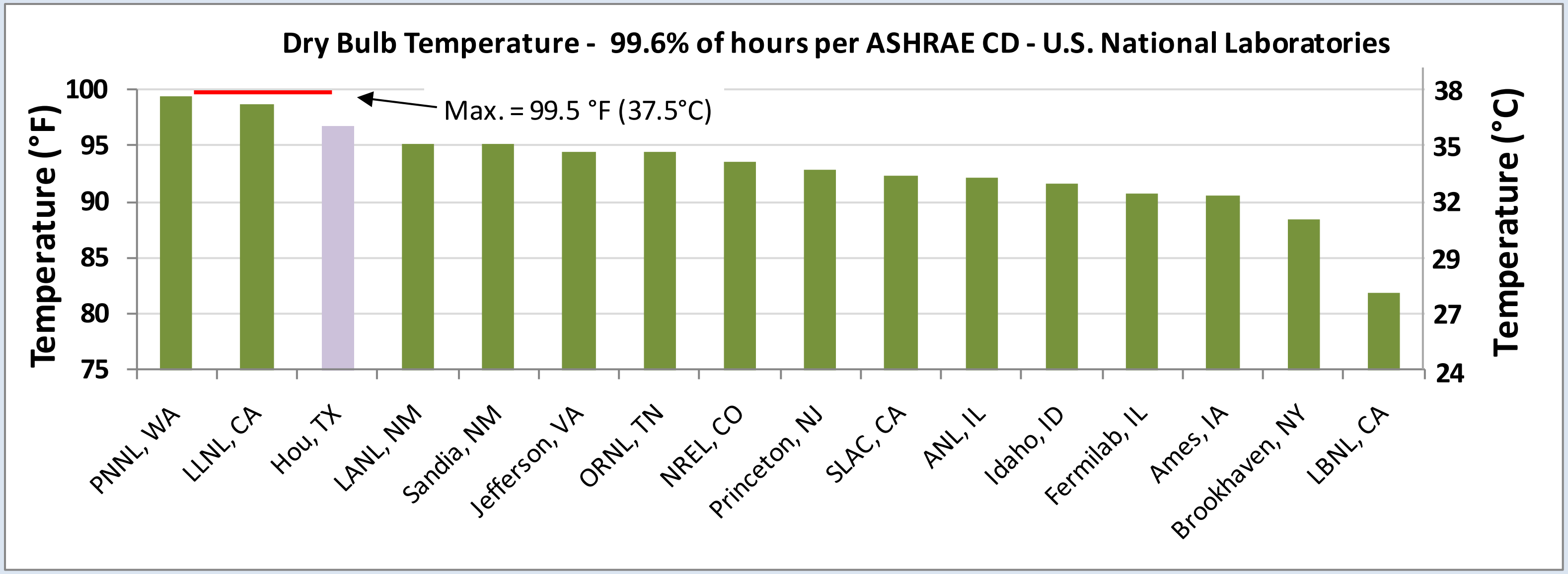
Select "typical" CPU – Intel 5545 @ 85 watts

Investigate Temperature changes throughout each system architecture (values from IT OEM's, other) to forecast cooling margins

Review results and agree on recommendation

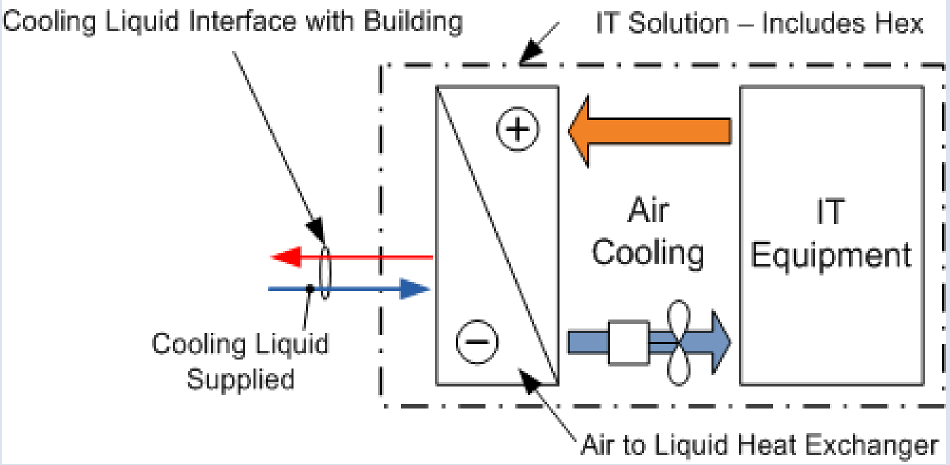
Wet and Dry Bulb Temperatures
ASHRAE data, 99.6% of yearly hours, National Laboratory HPC Locations.



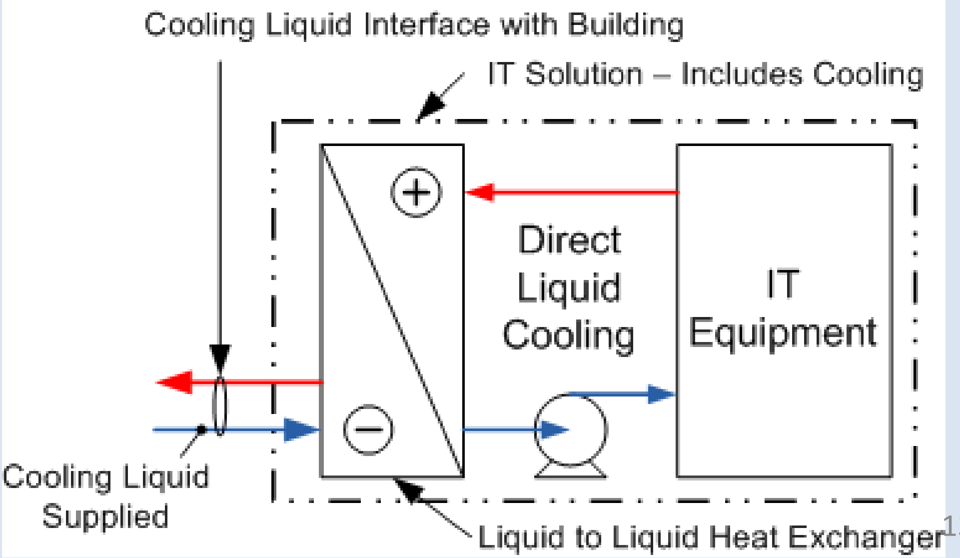


Examples : Air Cooling and Direct Liquid Cooling Architectures

Air Cooling
with Air to Liquid
Heat Exchanger

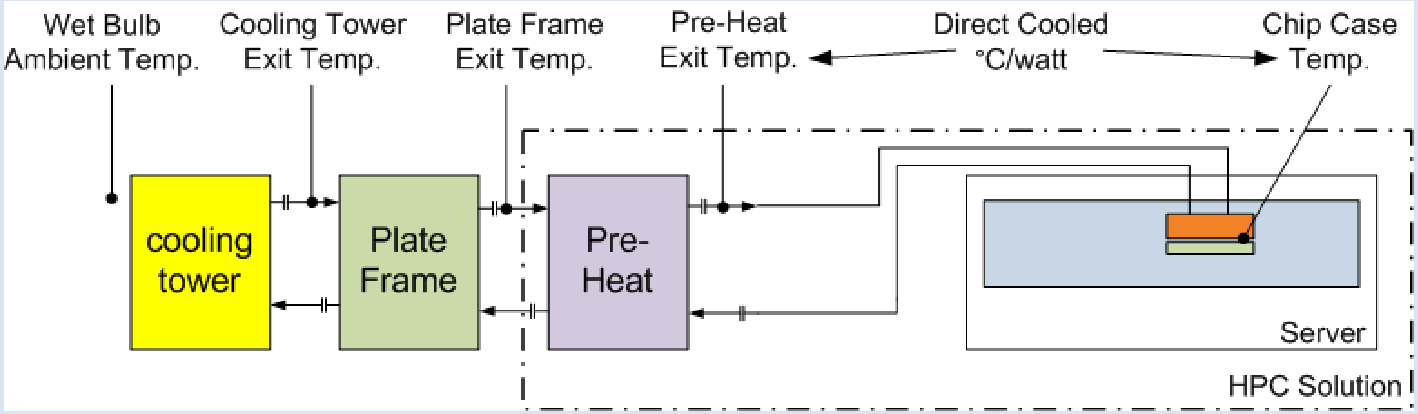


Direct Liquid Cooling
with Liquid to Liquid
Heat Exchanger

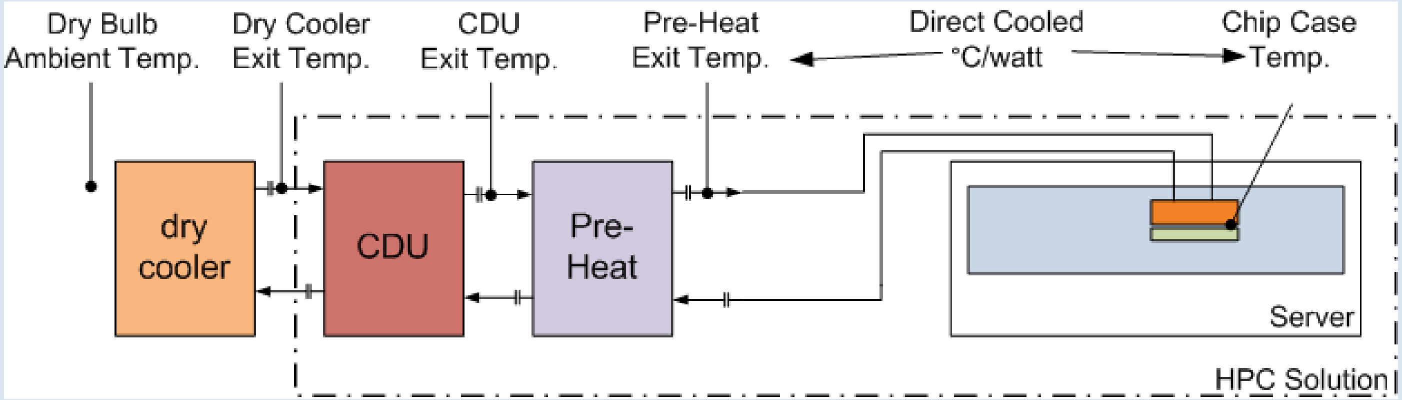


Direct Liquid Cooling Architectures

Cooling Tower

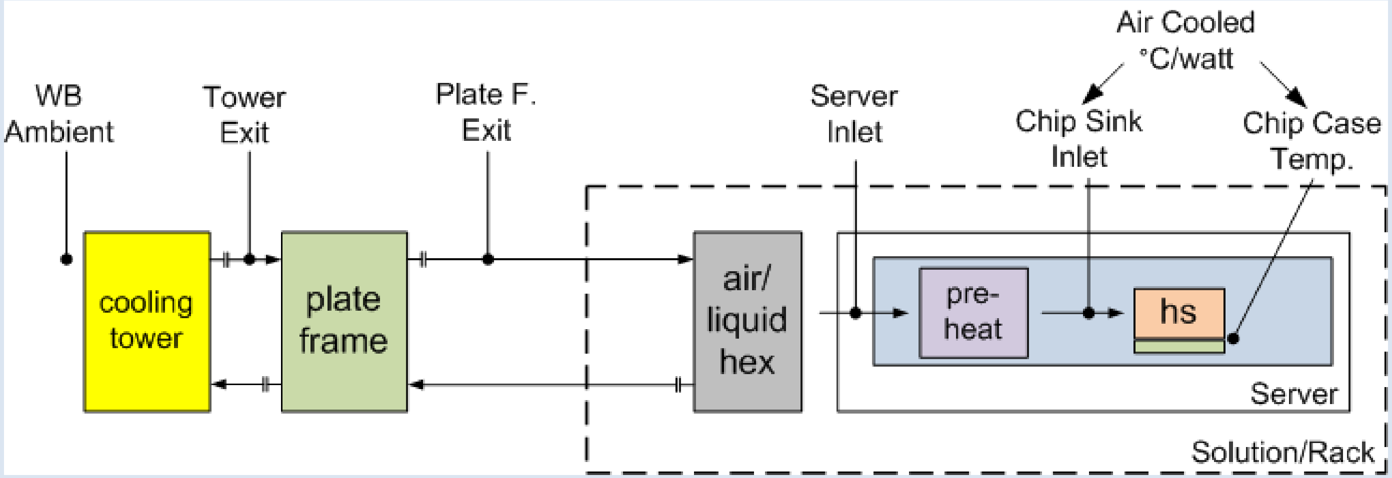


Dry Cooler

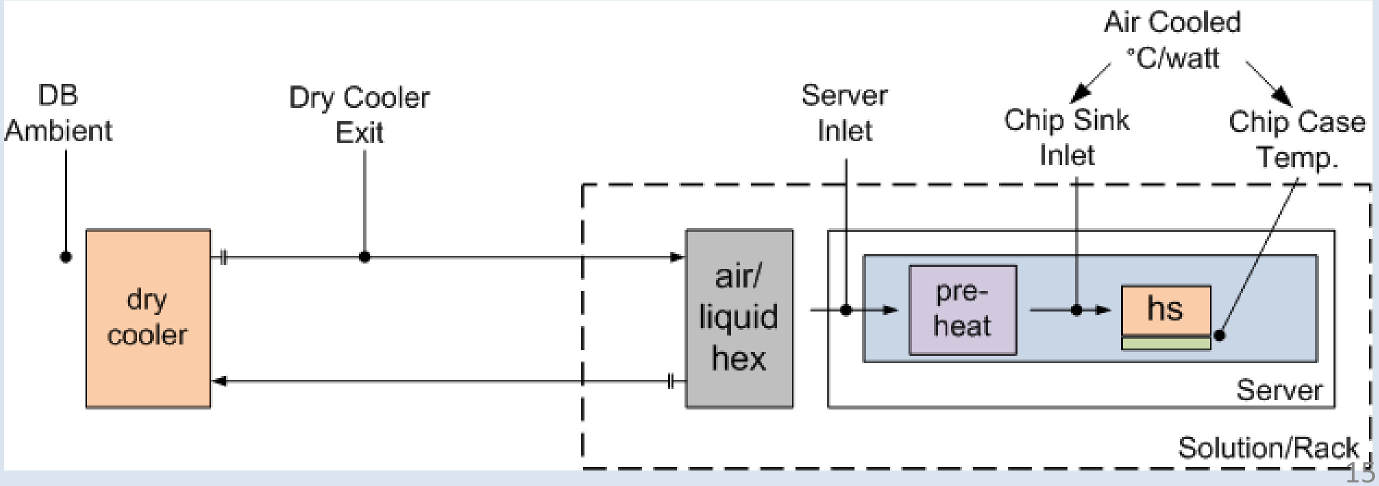


Air Cooling Architectures

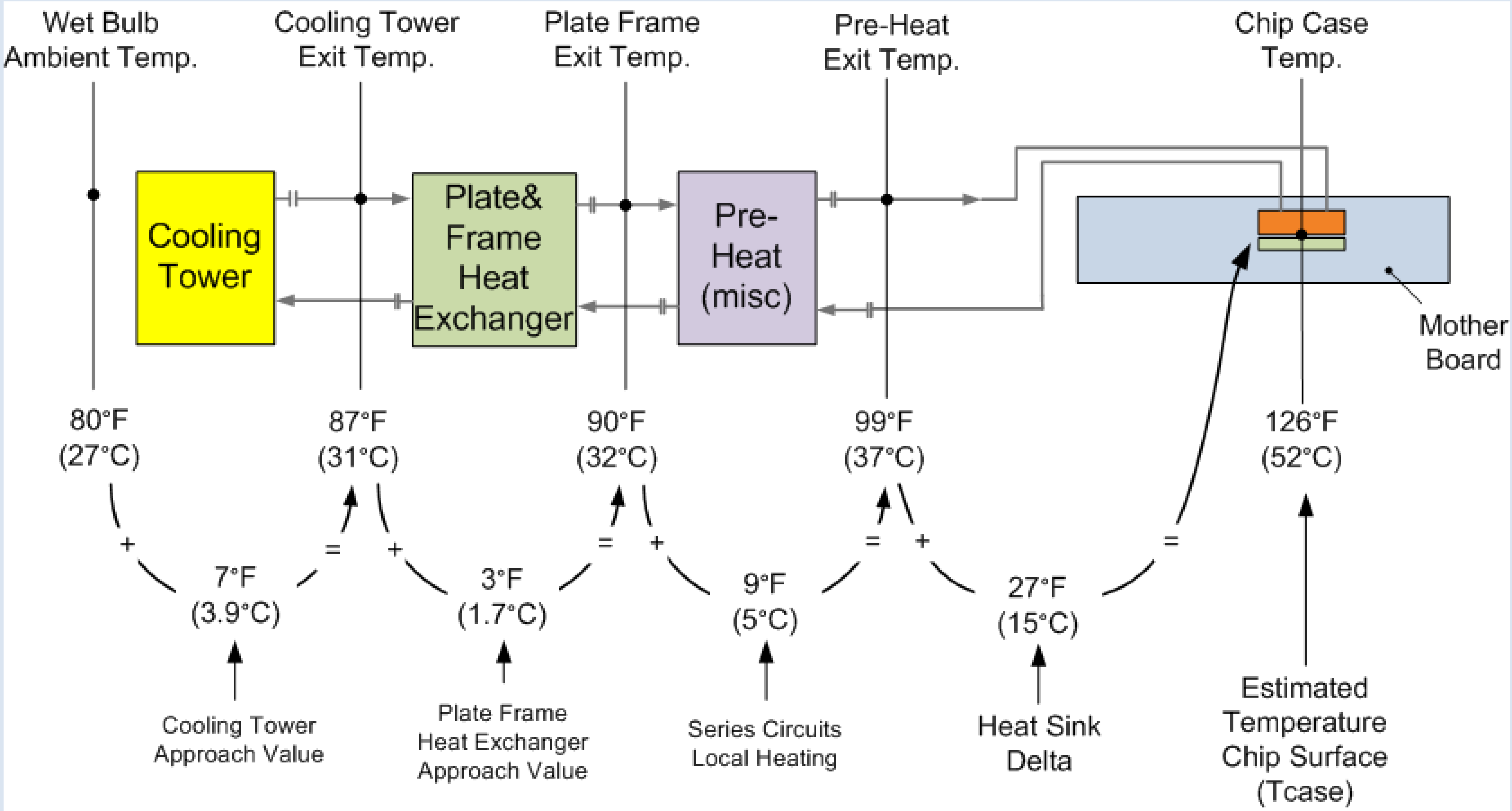
Cooling Tower



Dry Cooler



Chip Temperature Estimate
Using Temperature Difference (Approach) Summation
Example: Direct Liquid Cooling with Cooling Tower



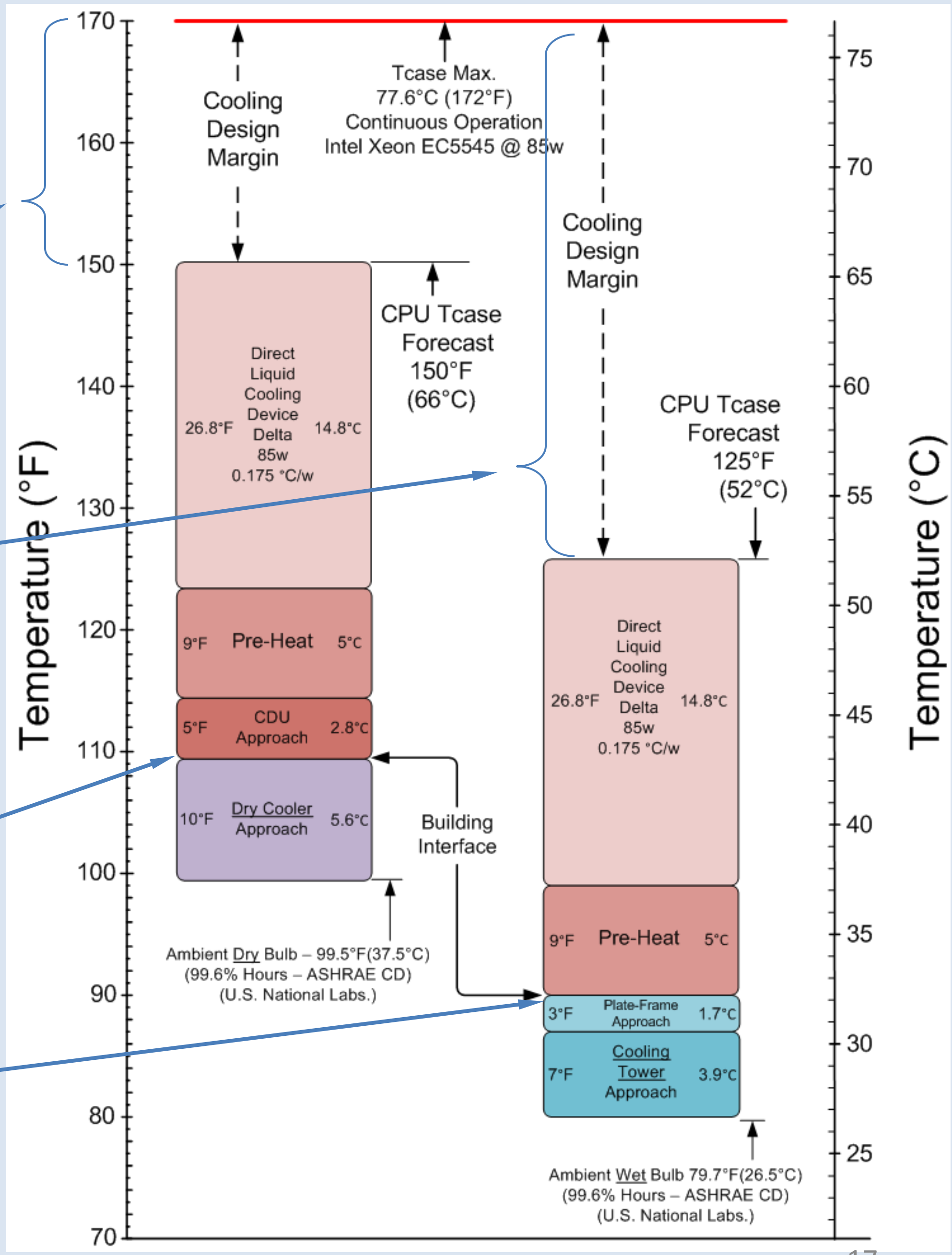
Direct Liquid Cooled Server
Dry Cooler and Cooling Tower

Chip Thermal Margin
22°F (12°C)
Using Dry Cooler Only

Chip Thermal Margin
47°F (26°C)
Using Cooling Tower Only

Using Dry Cooler Only
Water Temp. Supply from Building
109°F (43°C)

Using Cooling Tower Only
Water Temp. Supply from Building
89°F (32°C)



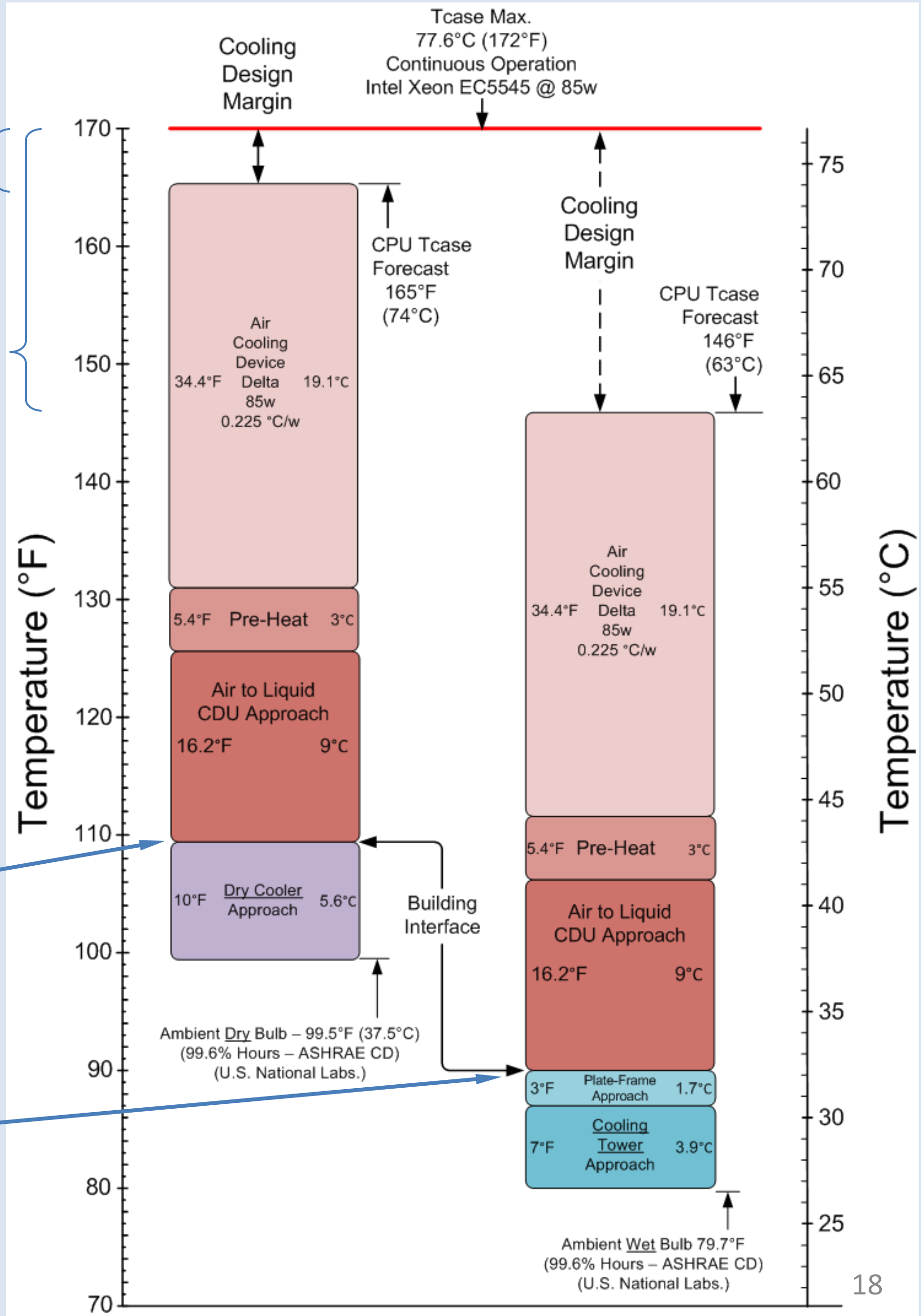
Air Cooled Server
Dry Cooler or Cooling Tower

Chip Thermal Margin
7°F (4°C)
Using <u>Dry Cooler Only</u>

Chip Thermal Margin
26°F (15°C)
Using <u>Cooling Tower Only</u>

Using Dry Cooler Only
Water Temp. Supply to Building
109°F (43°C)

Using Cooling Tower Only
Water Temp. Supply to Building
89°F (32°C)



Summary of Recommended Limits

Liquid Cooling Class	Main Cooling Equipment	Supplemental Cooling Equipment	Building Supplied Cooling Liquid Maximum Temperature
L1	Cooling Tower and Chiller	Not Needed	17 C (63 F)
L2	Cooling Tower	Chiller	32 C (89 F)
L3	Dry Cooler	Spray Dry Cooler, or Chiller	43 C (110 F)

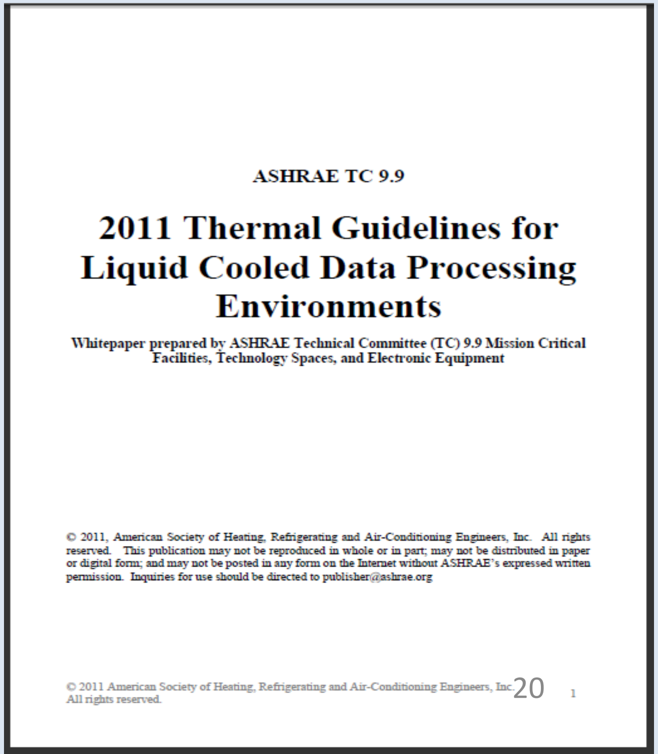
Conclusions

- Direct liquid cooling is practical using <u>only cooling towers</u> producing water supplied at 89°F (32°C) with thermal margin of 47°F (27°C)

- Direct liquid cooling is practical using <u>only dry coolers</u> producing water supplied at 109°F (43°C) with thermal margin of 22°F (12°C)

- The EE HPC User Group collaborated with HPC manufacturers and ASHRAE TC9.9 which included the recommended limits in its Liquid Cooling Thermal Guidelines white paper (2011)

- "Hot for Warm Water Cooling" paper available here:
  http://eehpcwg.lbl.gov/documents



ASHRAE TC 9.9

2011 Thermal Guidelines for Liquid Cooled Data Processing Environments

Whitepaper prepared by ASHRAE Technical Committee (TC) 9.9 Mission Critical Facilities, Technology Spaces, and Electronic Equipment

Next Steps

- Publicize the ability to cool with higher temperature liquids.
- ASHRAE revising Data Center Design and Operation book series
- Develop procurement specification guidance for HPC Users.
- HPC manufacturers develop high temperature liquid cooling solutions
- Inform Utility incentive programs

Questions